

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/05/2022

Details for "RC4136NE4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
RC4136NE4	NIPDAU	Level-NC-NC-NC	TI AGUASCALIENTES	N 14	6.35x19.3x4.57	1605.6

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.075626	99.998678	999987	0.00471	47
Precious Metals	Silver	7440-22-4	0.000001	0.001322	13	0	0
Sub-Total			0.075627	100	1000000	0.00471	47
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.471125	78.999968	790000	0.029343	293
Thermoplastics	Epoxy	85954-11-6	0.125236	21.000032	210000	0.0078	78
Sub-Total			0.596361	100	1000000	0.037143	371
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	381.125055	97.05	970500	23.737487	237375
Copper and Its Alloys	Iron	7439-89-6	10.21046	2.6	26000	0.635935	6359
Copper and Its Alloys	Phosphorus	7723-14-0	0.589065	0.15	1500	0.036689	367
Zinc and Its Alloys	Zinc	7440-66-6	0.78542	0.2	2000	0.048918	489
Sub-Total			392.71	100	1000000	24.459028	244590
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	1.33168	95.12	951200	0.082941	829
Precious Metals	Gold	7440-57-5	0.01092	0.78	7800	0.00068	7
Precious Metals	Palladium	7440-05-3	0.0574	4.1	41000	0.003575	36
Sub-Total			1.4	100	1000000	0.087196	872
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	1063.596453	88	880000	66.24363	662436
Other Plastics and Rubber	Carbon Black	1333-86-4	3.625897	0.3	3000	0.225831	2258
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	6.647478	0.55	5500	0.414023	4140
Thermoplastics	Epoxy	85954-11-6	134.762505	11.15	111500	8.393369	83934
Sub-Total			1208.632333	100	1000000	75.276852	752769
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.16867	100	1000000	0.135071	1351
Sub-Total			2.16867	100	1000000	0.135071	1351
Total			1605.582991			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality

For further environmental statements, please go to www.ti.com/ecoinfo

Created on: 06/05/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.